



Rear I/O

Features

- Fanless system with MB230 customized board
- 9th/8th Gen Intel® Core™ i7/i5/i3 Desktop Processors
- Dual SIM slots supports WWAN redundancy
- 4x RJ45 Gigabit Ethernet port (2x Supports 802.3at PoE+) 3x M.2 (B-Key/E-Key/M-Key)
- Supports Over/Under/Reverse voltage protection
- iSMART, iAMT (11.6), TPM (2.0)
- Flexible expansion slot system
- 2x 2.5" storage (Supports RAID 0/1)

Specifications

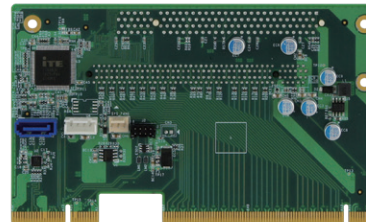
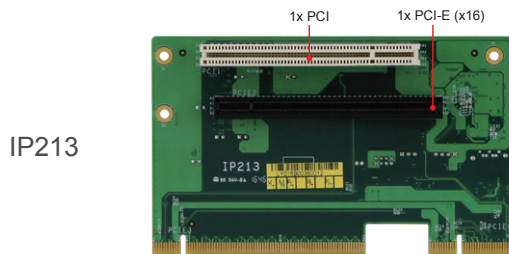
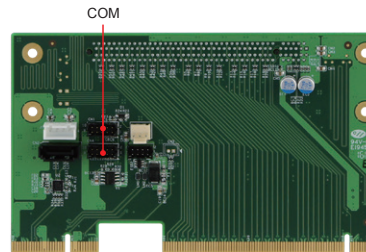
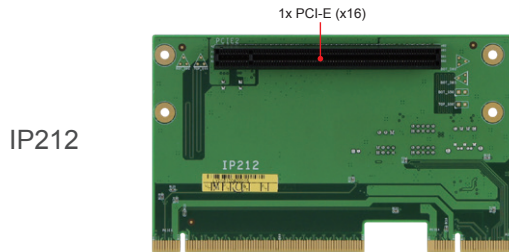
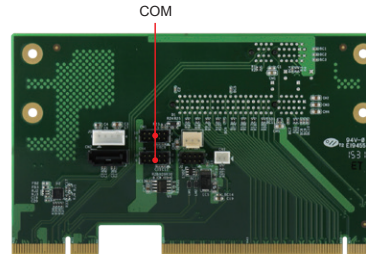
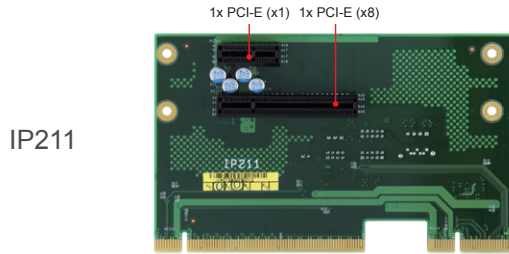
System Mainboard	MB230AF with Intel® Q370 PCH MB230AF-P with Intel® Q370 PCH (supports PCI-E function for M.2 (B-KEY))
CPU Type	9th/8th Gen Intel® Core™ i7/i5/i3 Desktop Processors
System Speed	Up to 4.00 GHz
Memory	2x DDR4-2666/2400 SO-DIMM, Max. 32GB
Construction	Aluminum & steel
Chassis Color	Silver + Gray (Aluminum)
Front Panel External I/O	1x RS232/422/485 port for COM#1~COM#2 3x RS232 ports for COM#3~COM#4 2x RS232 ports for COM#5~6 from optional IP211/IP212 1x DisplayPort (1.2) 2x RJ45 Gigabit Ethernet port (Supports 802.3at PoE+) 1x 5-pins DC-in terminal block type for 12V(±10%) or 18V(-10%)~24V(+10%) 2x Antenna holes 2x USB 2.0 from optional IP211/IP212/IP213 2x expansion slot
Rear Panel External I/O	1x DVI-D + HDMI(1.4) 4x USB3.1 ports 2x Antenna holes 2x RJ45 Gigabit Ethernet port + Dual USB3.1 stack ports 1x Red HDD LED 1x power button with Green LED indicator 1x 2-pin terminal block 2x SIM Card (AMI231AF-P only supports 1x SIM Card)
Expansion	IP211/IP212/IP213
Storage / M.2	2x 2.5" HDD/SSD 1x M.2 (B-KEY Supports USB2.0 for 4G/LTE) 1x M.2 (E-KEY Supports PCI-E + USB2.0 for CNVi) 1x M.2 (M-KEY Supports PCI-E(4x) + SATA for NVMe SSD)
Mounting	Desktop & wall mount
Dimensions	210mm(W) x 285mm(D) x 129mm(H)
Weight	4.9 kg

Operating Temperature	-20°C to 70°C (-4°F~158°F) (for 35W CPU)
Storage Temperature	-20°C~80°C (-4°F~176°F)
Relative Humidity	5%~90%@45°C (non-condensing)
Vibration	Operating : 3Grms / 5~500Hz
Shock	Operating : 20G / 11ms Non-operating : 40G / 11ms
Certification	CE/ FCC ClassA/ LVD

Ordering Information

AMI232AF (Supports SIERRA module)	Fanless box System with MB230AF, w/ Intel® Core™ i7/i5/i3 desktop Processor, 6x COM (from IP211/ IP212) 4x COM (from IP213), 1x 8GB memory, 1x 2.5" 64GB MLC industrial-grade SSD, w/o power adaptor, optional riser card
AMI232AF-P	Fanless box System with MB230AF-P, w/ Intel® Core™ i7/i5/i3 desktop Processor, 6x COM (from IP211/ IP212) 4x COM (from IP213), 1x 8GB memory, 1x 2.5" 64GB MLC industrial-grade SSD, w/o power adaptor, optional riser card
330W Power Adaptor Kit (optional)	330W (24V(±10%)(@13.75A) power adaptor Kit Compatible with IEC62368-1/EN62368-1
Riser card kit (optional)	IP211 (ZM05IP211---0B1000R) w/ COM cable (2x C501PK1H009302A00P) IP212 (ZM05IP212---0A1000R) w/ COM cable (2x C501PK1H009302A00P) IP213 (ZM05IP213---0A1000R) w/o COM cable
Optional Accessories	Global 4G antenna kit for Sierra Wireless EM7565 module, M.2 (M-KEY 2280) Thermal kit

Expansion Cards



Dimensions and Drawing

